

ABSTRACT

5 APPARATUS AND METHOD OF PLACING
 SOLDER BALLS ONTO A SUBSTRATE

10 The invention provides an apparatus and method for positioning solder balls
 in a desired array on a substrate. A positioning means is provided for
 positioning the solder balls in positions corresponding to the array of positions
 the solder balls are to take up on the substrate. A container for receiving a
 plurality of solder balls and which is movable between a first position remote
 from the positioning means and a second position directly thereover supplies
 solder balls to the positioning means. Means are provided to bias the solder
15 balls in the direction of movement of the container from the first to the second
 position whereby to reduce or obviate damage to the solder balls during such
 movement.

(Fig 2a)

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